

Title (en)  
DIFFUSION BONDING OF DISSIMILAR CERAMICS

Publication  
**EP 0093199 B1 19870520 (EN)**

Application  
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Priority  
US 37392682 A 19820503

Abstract (en)  
[origin: US4406722A] Diffusion bonding of dissimilar ceramics can be accomplished by the application of pressure only while the ceramics are at a temperature at which their expansion rates are the same. A process for manufacturing magnetic head cores is disclosed where a magnetic ferrite is diffusion bonded to a non-magnetic ceramic by heating the core pieces to the expansion rate crossover temperature and then applying the diffusion bonding pressure. The pressure is removed either before or after the bonded pieces are cooled.

IPC 1-7  
**C04B 37/00**; **G11B 5/193**

IPC 8 full level  
**C04B 37/00** (2006.01); **G11B 5/127** (2006.01); **G11B 5/133** (2006.01)

CPC (source: EP US)  
**C04B 35/4686** (2013.01 - EP US); **C04B 35/645** (2013.01 - EP US); **C04B 37/001** (2013.01 - EP US); **C04B 37/005** (2013.01 - EP US); **G11B 5/1335** (2013.01 - EP US); **C04B 2235/3232** (2013.01 - EP US); **C04B 2235/3244** (2013.01 - EP US); **C04B 2235/3418** (2013.01 - EP US); **C04B 2235/656** (2013.01 - EP US); **C04B 2235/6562** (2013.01 - EP US); **C04B 2235/6565** (2013.01 - EP US); **C04B 2235/6567** (2013.01 - EP US); **C04B 2235/80** (2013.01 - EP US); **C04B 2235/9607** (2013.01 - EP US); **C04B 2237/10** (2013.01 - EP US); **C04B 2237/32** (2013.01 - EP US); **C04B 2237/34** (2013.01 - EP US); **C04B 2237/341** (2013.01 - EP US); **C04B 2237/343** (2013.01 - EP US); **C04B 2237/346** (2013.01 - EP US); **C04B 2237/348** (2013.01 - EP US); **C04B 2237/36** (2013.01 - EP US); **C04B 2237/52** (2013.01 - EP US); **C04B 2237/62** (2013.01 - EP US); **C04B 2237/78** (2013.01 - EP US); **Y10T 29/49055** (2015.01 - EP US)

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**US 4406722 A 19830927**; DE 3276366 D1 19870625; EP 0093199 A2 19831109; EP 0093199 A3 19850515; EP 0093199 B1 19870520; JP S58190879 A 19831107; JP S6219398 B2 19870428

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